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B24B 37/04**G01B 7/00****H01L 21/304**(21) Application number: **09215658**(71) Applicant: **NEC CORP**(22) Date of filing: **25.07.97**(72) Inventor: **SATO UICHI**(54) **POLISHING AMOUNT CONTROL DEVICE**

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(57) Abstract:

PROBLEM TO BE SOLVED: To provide a polishing amount control device whereby a local residual film thickness of a wafer can be measured, so as to prevent a bad influence from being given to a characteristic of a semiconductor chip by measuring applied voltage.

SOLUTION: Opposed to an electrode 2 in a dicing area formed in a wafer 1, a measuring electrode 9 is divisionally arranged in a polishing pad 8. In a wafer hold means 6 in a side of the wafer 1, a correction electrode 5 is provided, on the other hand, a correcting measuring electrode 10 is left as provided in a position opposed to the correction electrode 5 of the polishing pad 8. In this condition, polishing is performed, and a static capacity between the electrode 2 and the measuring electrode 9 is obtained. In accordance with a of this measured capacity value, pressure of air is applied from a local pressure hole 6a, an inter-layer insulating film 11 of the wafer is pressed to a side of the pad 8, and polishing is performed in this pressed condition.

